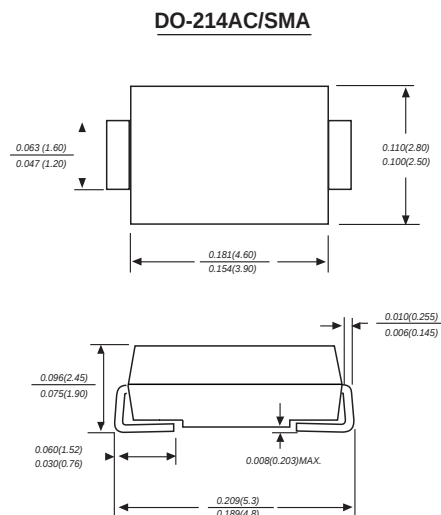


FEATURES

- LOW PROFILE PACKAGE
- PLASTIC PACKAGE HAS UNDERWRITERS LABORATORY 94V-0
- IDEAL FOR SURFACE MOUNTED APPLICATION
- GLASS PASSIVATED CHIP JUNCTION
- BUILT-IN STRAIN RELIEF DESIGN
- ULTRA FAST RECOVERY TIME FOR HIGH EFFICIENT
- HIGH TEMPERATURE SOLDERING: 250°C/10 SECONDS AT TERMINALS

MECHANICAL DATA

- CASE: JEDEC DO-214AC MOLDED PLASTIC BODY, DIMENSIONS IN INCHES AND (MILLIMETERS)
- TERMINAL: SOLDER PLATED, SOLDERABLE PER MIL-STD-750 METHOD 2026
- POLARITY: COLOR BAND DENOTES CATHODE
- WEIGHT: 0.069 GRAMS



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

RATINGS AT 25°C AMBIENT TEMPERATURE UNLESS OTHERWISE SPECIFIED
SINGLE PHASE, HALF WAVE, 60 HZ, RESISTIVE OR INDUCTIVE LOAD.
FOR CAPACITIVE LOAD, DERATE CURRENT BY 20%

RATINGS	SYMBOL	MURA 105	MURA 110	MURA 115	MURA 120	MURA 140	MURA 160	UNITS
MAXIMUM RECURRENT PEAK REVERSE VOLTAGE	V_{RRM}	50	100	150	200	400	600	V
MAXIMUM RMS VOLTAGE	V_{RMS}	35	70	105	140	280	420	V
MAXIMUM DC BLOCKING VOLTAGE	V_{DC}	50	100	150	200	400	600	V
MAXIMUM AVERAGE FORWARD RECTIFIED CURRENT AT $T_L=75^\circ\text{C}$	I_O	1.0						A
PEAK FORWARD SURGE CURRENT, 8.3ms SINGLE HALF SINE-WAVE SUPERIMPOSED ON RATED LOAD	I_{FSM}	35						A
TYPICAL JUNCTION CAPACITANCE (NOTE 1)	C_J	50						PF
TYPICAL THERMAL RESISTANCE (NOTE 2)	$R_{\theta JL}$	15						°C/W
STORAGE TEMPERATURE RANGE	T_{STG}	-55 TO + 150						°C
OPERATING TEMPERATURE RANGE	T_{OP}	-55 TO + 150						°C

ELECTRICAL CHARACTERISTICS ($A_T T_A=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

CHARACTERISTICS	SYMBOL	MURA 105	MURA 110	MURA 115	MURA 120	MURA 140	MURA 160	UNITS
MAXIMUM FORWARD VOLTAGE AT I_O DC	V_F	0.90				1.28		V
MAXIMUM DC REVERSE CURRENT AT $T_A=25^\circ\text{C}$	I_R	2				5		μA
MAXIMUM DC REVERSE CURRENT AT $T_A=125^\circ\text{C}$	I_R	250						μA
MAXIMUM REVERSE RECOVERY TIME (NOTE 3)	T_{RR}	30				50		nS

- NOTES : 1. MEASURED AT 1 MHZ AND APPLIED REVERSE VOLTAGE OF 4.0 VOLTS
2. THERMAL RESISTANCE FROM JUNCTION TO AMBIENT AND JUNCTION TO LEAD P.C.B. MOUNTED ON 0.3×0.3" (8.0×8.0 mm) COPPER PAD AREAS
3. REVERSE RECOVERY TEST CONDITIONS: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

FIG. 1-TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC

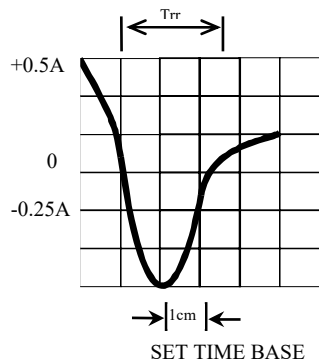


FIG. 2-TYPICAL FORWARD CURRENT DERATING CURVE

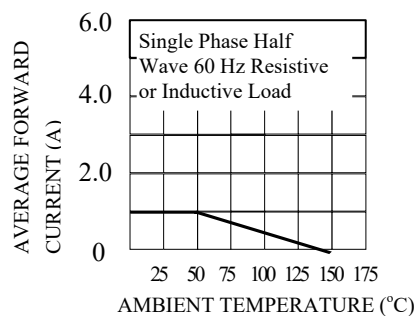


FIG. 3-TYPICAL REVERSE CHARACTERISTICS

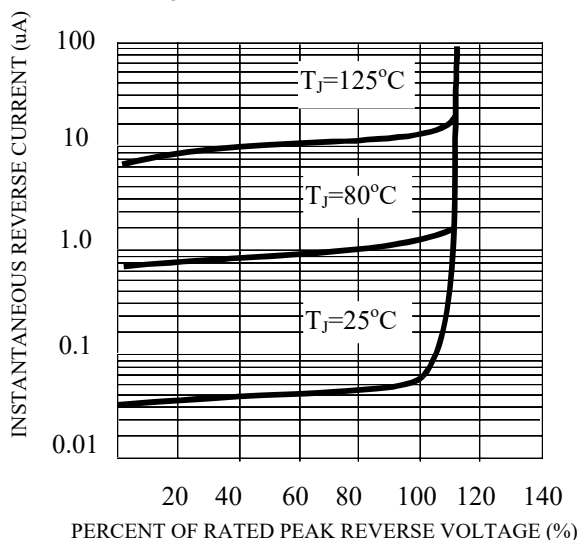


FIG. 4-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

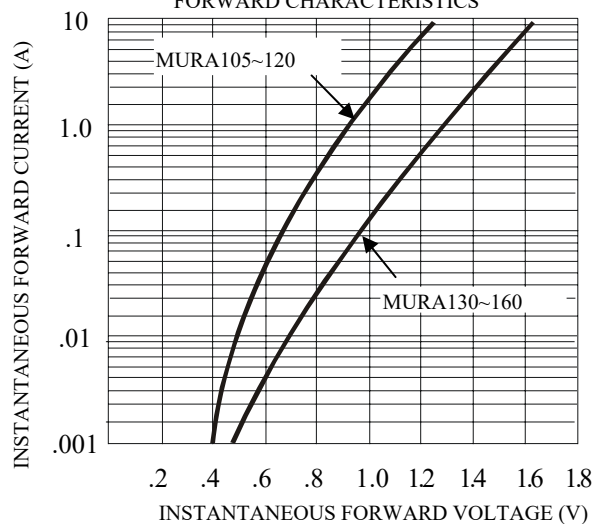


FIG. 5-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

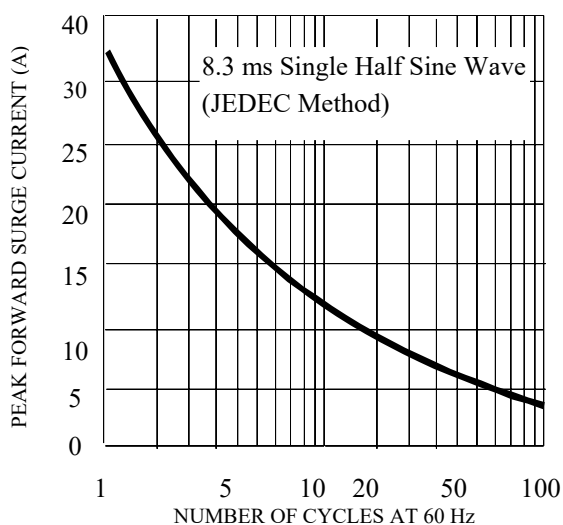
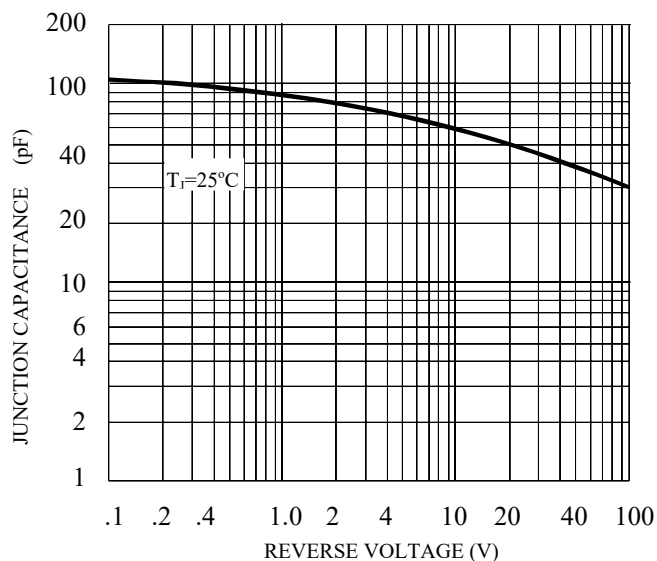
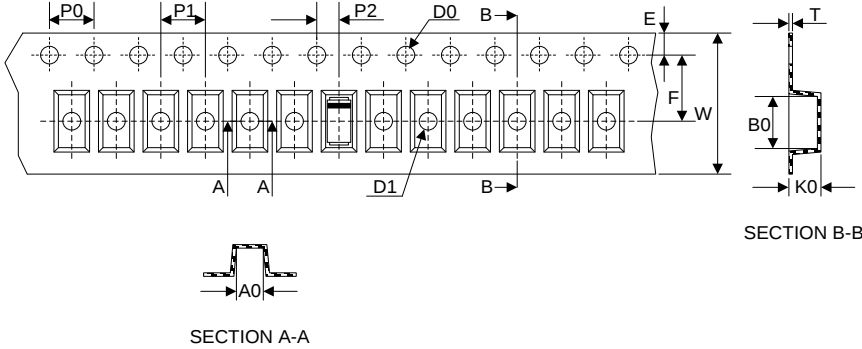
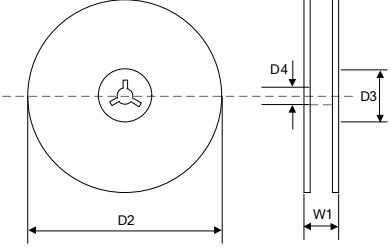
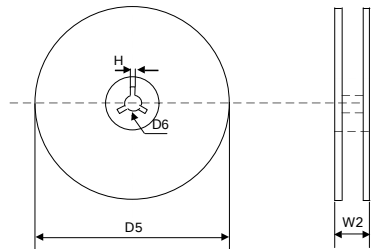


FIG. 6-TYPICAL JUNCTION CAPACITANCE



Packaging

Tape 	Symbol	Dimension (mm)
	W	12.00±0.20
	P0	4.00±0.10
	P1	4.00±0.10
	P2	2.00±0.10
	D0	Φ1.5±0.10
	D1	Φ1.5±0.10
	E	1.75±0.10
	F	5.50±0.05
	A0	2.79±0.10
	B0	5.33±0.10
	K0	2.55±0.15
	T	0.25±0.05
7" Reel 	D2	Φ178.0±2.0
	D3	Φ50.0Min.
	D4	Φ13.0±0.5
	W1	16.0±2.0
	Quantity: 2000PCS	
11" Reel 	D5	Φ280.0±2.0
	D6	Φ13.5±0.5
	H	2.5±1.0
	W2	16.0±2.0
	Quantity: 5000PCS	